

HIGH-SPEED EDGE CARD SYSTEMS

0.60 mm, 0.80 mm and 1.00 mm PITCH



FEATURES & BENEFITS

- Maximum Design Flexibility
- Up to 64 Gbps PAM4 performance
- PCI Express® 3.0, 4.0, 5.0 and 6.0
- Edge Rate[®] contacts optimized for signal integrity performance and high-cycle life
- Up to 200 positions available
- Vertical, right-angle, edge mount, pass-through orientations
- Power/signal combo, press-fit tails, rugged weld tabs, locks and latches
- Mating cable assemblies available



Rugged tucked beam technology (HTEC8)



Differential pair for increased speed (HSEC8-DP)



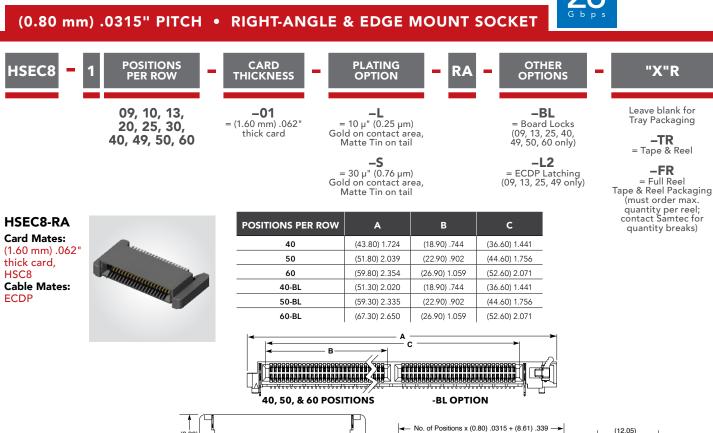
Custom designs allow for misalignment in the X-Y axes (HSEC1)

KEY SPECIFICATIONS

SERIES	PITCH	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
HSEC6	0.60 mm	56-168	Black LCP	Copper Alloy	-55 °C to +125 °C	1.9 A (2 pins)	240 VAC	Yes
HTEC8	0.80 mm	20-200	Black LCP	Copper Alloy	-55 °C to +125 °C	3.0 A (2 pins)	215 VAC	Yes
HSEC8	0.80 mm	18-200	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC	Yes
HSEC1	1.00 mm	20-140	Black LCP	Phosphor Bronze	-55 °C to +125 °C	2.2 A (2 pins)	215 VAC	Yes





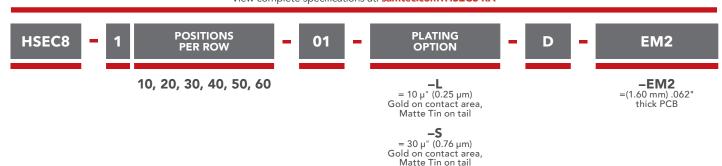


View complete specifications at: samtec.com?HSEC8-RA

10, 20 & 30 POSITIONS

No. of Positions x (0.80) .0315 + (5.38) .212

(1.25)



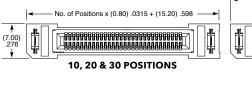
HSEC8-EM

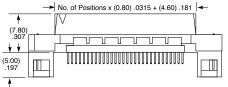
Card Mates: (1.60 mm) .062" thick card, HSC8 **Cable Mates: ECDP**



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Note: Some sizes, styles and options are non-standard, non-returnable.





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No. of Positions x (0.80) .0315 + (18.40) .724 No. of Positions x (0.80) .0315 + (7.80) .307 40, 50 & 60 POSITIONS

POSITIONS PER ROW Α В 40 (18.90) .744 (36.60) 1.441 50 (22.90) .902 (44.60) 1.756 60 (26.90) 1.059 (52.60) 2.071

(12.05)